Lead-free Solders in Microelectronics

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Citation Report

#	Article	IF	Citations
1	Green packages-requirements, materials, results. , 0, , .		7
2	Effect of Cu-containing solders on the critical IMC thickness for the shear strength of BGA solder joints. , 0, , .		6
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4	Investigation of UBM systems for electroplated Sn/37Pb and Sn/3.5Ag solder. , 2001, , .		2
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8	Effects of microstructural evolution and intermetallic layer growth on shear strength of ball-grid-array Sn-Cu solder joints. Journal of Electronic Materials, 2001, 30, 1323-1331.	2.2	39
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